

**AMENDMENTS TO THE CLAIMS**

1-24. (Cancelled)

25. (Currently amended) A heat-treating method for a packaging product, comprising:  
providing a packaging product formed by enclosing a content material within a  
packaging material ~~comprising at least a layer of hydrophilic gas-barrier resin selected from  
the group consisting of ethylene-vinyl alcohol copolymer,  
polymetaxylylene adipamide and glycolic acid (co-)polymer, and~~  
heat-treating the packaging product with hot water;

wherein the packaging material has a multi-layer structure including an outer surface  
layer of at least one hydrophobic resin selected from the group consisting of polyolefins,  
olefin copolymers, aromatic polyesters, aromatic polyamides, aliphatic polyamides, and  
styrene resins, and an inner layer of hydrophilic gas-barrier resin selected from the group  
consisting of ethylene-vinyl alcohol copolymer, polymetaxylylene adipamide and glycolic  
acid (co-)polymer, and

wherein the hot water is caused to contain a water-soluble compound, and ~~wherein~~  
the water-soluble compound is an inorganic electrolyte.

26. (Previously presented) The heat-treating method according to Claim 25, wherein the  
hot water has a temperature of 60-100°C to effect a boiling heat-treatment.

27. (Previously presented) The heat-treating method according to Claim 25, wherein the  
hot water has a temperature exceeding 100°C to effect a retort heat-treatment.

28. (Previously presented) The heat-treating method according to Claim 25, wherein the  
hot water contains the water-soluble compound at a concentration exceeding 0.1 wt.%.

29. (Previously presented) The heat-treating method according to Claim 25, wherein the  
hot water contains the water-soluble compound at a concentration of at least 1 wt.%.

30. (Cancelled)

31. (Previously presented) The heat-treating method according to Claim 25, wherein the water-soluble compound is a water-soluble inorganic salt.

32. (Previously presented) The heat-treating method according to Claim 31, wherein the water-soluble compound is a chloride selected from the group consisting of sodium chloride, magnesium chloride, and potassium chloride.

33. (Previously presented) The heat-treating method according to Claim 32, wherein the water-soluble compound is sodium chloride.

34-39. (Cancelled)

40. (Currently amended) The heat-treating method according to Claim ~~39~~25, wherein the hydrophilic gas-barrier resin layer is disposed as a surface layer contacting the hot water.

41. (Currently amended) The heat-treating method according to Claim ~~39~~25, wherein the hydrophilic gas-barrier resin layer is disposed as an inner layer not directly contacting the hot water.

42. (Previously presented) The heat-treating method according to Claim 41, wherein the gas-barrier resin is glycolic acid (co-)polymer.

43. (Withdrawn) A packaged product, which has been heat-treated by a heat-treating method according to Claim 25.

44. (Withdrawn) A packaged product according to Claim 43, wherein the heat-treated packaging material has a haze below 20%.

45. (Withdrawn) A heat-treated packaged product, comprising a heat-treated packaging material having a multi-layer structure including an inner layer of a hydrophilic gas-barrier resin layer selected from the group consisting of ethylene-vinyl alcohol copolymer and glycolic acid (co-)polymer, and a content material enclosed within the packaging material, wherein the heat-treated packaging material has a haze below 20%.
46. (Withdrawn) A packaged product according to Claim 45, wherein the hydrophilic gas-barrier resin is ethylene-vinyl alcohol copolymer.
47. (Withdrawn) A packaged product according to Claim 45, wherein the hydrophilic gas-barrier resin is glycolic acid (co-)polymer.
48. (Withdrawn) A packaged product according to Claim 43, wherein the packaged material has been subjected to a heat-shrinking treatment during the heat treatment.